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Then click **Search Again**.**Results:**Journal or Magazine = **JNL** Conference = **CNF** Standard = **STD****1 Comparison of electrical and reliability characteristics of different : Aring/ oxynitride gate dielectrics***Tung-Ming Pan; Hsiu-Shan Lin; Main-Gwo Chen; Chuan-Hsi Liu; Yih-Jau Cha*

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